



- ☐ Drafts
- ☐ Pending
- ☒ Active
  - ☒ L1: (6) probing adj damage
  - ☒ L2: (170660) probe or prob
  - ☒ L3: (1545) 2 and bonding a
  - ☒ L4: (31) 3 and (first adj
- ☐ Failed

 Search    
DBs:  USPAT:EPD:JPO☒ PluralsDefault operator:  OR☒ Highlight all hit terms

3 and (first adj pad and second adj pad)

    

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRe
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6351405 B1	20020226	11	Pad for integrated circuit device which allows for	365/63	365/201; 439/169;
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6303948 B1	20011016	23	Pad layout and lead layout in semiconductor device	257/207	257/773; 257/786;
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6140212 A	20001031	4	Semiconductor device and method therefor	438/467	438/333; 438/601
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6096567 A	20000801	37	Method and apparatus for direct probe sensing	438/14	324/758; 438/16;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5982042 A	19991109	24	Semiconductor wafer including semiconductor	257/786	257/203; 257/48;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5896040 A	19990420	11	Configurable probe pads to facilitate parallel testing	324/763	324/765
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5896039 A	19990420	11	Configurable probe pads to facilitate parallel testing	324/763	324/765
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5767527 A	19980616	23	Semiconductor device suitable for testing	257/48	257/669; 257/674;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5648661 A	19970715	45	Integrated circuit wafer comprising unsingulated	257/48	257/208; 257/620;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5532612 A	19960702	19	Methods and apparatus for test and burn-in of	324/760	324/754
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5444254 A	19950822	12	Flexible radiation probe	250/370.07	250/370.14